life. augmented

## STD20NF10T4

## N-channel 100 V, $0.038 \Omega$ typ., 25 A STripFET ${ }^{\text {TM }}$ II Power MOSFET in a DPAK package

Datasheet - production data


Figure 1: Internal schematic diagram


Features

| Order code | V $_{\text {DS }}$ | RDS(on) max. | ID $^{\text {m }}$ |
| :---: | :---: | :---: | :---: |
| STD20NF10T4 | 100 V | $0.045 \Omega$ | 25 A |

- Exceptional dv/dt capability
- Application oriented characterization


## Applications

- Switching applications


## Description

This Power MOSFET series realized with STMicroelectronics unique STripFET ${ }^{\text {TM }}$ process is specifically designed to minimize input capacitance and gate charge. It is therefore ideal as a primary switch in advanced high-efficiency isolated DC-DC converters for Telecom and Computer applications. It is also suitable for any application with low gate charge drive requirements.

Table 1: Device summary

| Order code | Marking | Package | Packing |
| :---: | :---: | :---: | :---: |
| STD20NF10T4 | D20NF10 | DPAK | Tape and <br> reel |

## Contents

1 Electrical ratings ..... 3
2 Electrical characteristics ..... 4
2.1 Electrical characteristics (curves) ..... 6
3 Test circuits ..... 8
4 Package information ..... 9
4.1 DPAK (TO-252) type A package information ..... 9
4.2 DPAK (TO-252) type C package information ..... 11
4.3 DPAK (TO-252) packing information ..... 14
5 Revision history ..... 16

Electrical ratings
Table 2: Absolute maximum ratings

| Symbol | Parameter | Value | Unit |
| :---: | :---: | :---: | :---: |
| VDS | Drain-source voltage | 100 | V |
| V ${ }_{\text {dgr }}$ | Drain-gate voltage ( $\mathrm{RGS}^{\text {a }}=20 \mathrm{k} \Omega$ ) | 100 | V |
| $\mathrm{V}_{\mathrm{GS}}$ | Gate-source voltage | $\pm 20$ | V |
| ID | Drain current (continuous) at $\mathrm{T}_{\mathrm{C}}=25^{\circ} \mathrm{C}$ | 25 | A |
| ID | Drain current (continuous) at $\mathrm{T}_{\mathrm{C}}=10{ }^{\circ} \mathrm{C}$ | 21 | A |
| $\mathrm{IDM}^{(1)}$ | Drain current (pulsed) | 100 | A |
| $\mathrm{P}_{\text {TOT }}$ | Total dissipation at $\mathrm{T}_{\mathrm{C}}=25^{\circ} \mathrm{C}$ | 85 | W |
| $\mathrm{EAS}^{(2)}$ | Single pulse avalanche energy | 300 | mJ |
| $\mathrm{dv} / \mathrm{dt}{ }^{(3)}$ | Peak diode recovery voltage slope | 20 | V/ns |
| $\mathrm{T}_{\mathrm{j}}$ | Operating junction temperature range | - 55 to 175 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\text {stg }}$ | Storage temperature range |  |  |

## Notes:

${ }^{(1)}$ Pulse width limited by safe operating area.
${ }^{(2)}$ Starting $T_{J}=25^{\circ} \mathrm{C}, I_{D}=10 \mathrm{~A}, \mathrm{~V}_{D D}=27 \mathrm{~V}$.
${ }^{(3)}{ }_{\text {ISD }} \leq 25 \mathrm{~A}, \mathrm{di} / \mathrm{dt} \leq 300 \mathrm{~A} / \mu \mathrm{s} ; \mathrm{V}_{\mathrm{DD}}=\mathrm{V}_{(\mathrm{BR}) \mathrm{DSS},} \mathrm{T}_{\mathrm{J}} \leq$ TJMAX.

Table 3: Thermal data

| Symbol | Parameter | Value | Unit |
| :---: | :--- | :---: | :---: |
| Rthj-case | Thermal resistance junction-case | 1.76 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| $\mathrm{R}_{\text {thjpcb }}{ }^{(1)}$ | Thermal resistance junction-pcb | 50 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |

## Notes:

${ }^{(1)}$ When mounted on 1 inch $^{2}$ FR-4, 2 Oz copper board.

## 2 Electrical characteristics

$\mathrm{T}_{\mathrm{C}}=25^{\circ} \mathrm{C}$ unless otherwise specified
Table 4: On/off-state

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $V_{\text {(BR) }}$ DSS | Drain-source breakdown voltage | $\mathrm{VGS}=0 \mathrm{~V}, \mathrm{ld}=250 \mu \mathrm{~A}$ | 100 |  |  | V |
| Idss | Zero-gate voltage drain current | $\mathrm{V}_{\mathrm{GS}}=0 \mathrm{~V}, \mathrm{~V}_{\mathrm{DS}}=100 \mathrm{~V}$ |  |  | 1 | $\mu \mathrm{A}$ |
|  |  | $\begin{aligned} & V_{G S}=0 \mathrm{~V}, \mathrm{~V}_{\mathrm{DS}}=100 \mathrm{~V} \\ & \mathrm{~T}_{\mathrm{C}}=125^{\circ} \mathrm{C}{ }^{(1)} \end{aligned}$ |  |  | 10 | $\mu \mathrm{A}$ |
| IGSS | Gate body leakage current | $\mathrm{V}_{\mathrm{DS}}=0 \mathrm{~V}, \mathrm{~V}_{\mathrm{GS}}= \pm 20 \mathrm{~V}$ |  |  | $\pm 100$ | nA |
| VGS(th) | Gate threshold voltage | $\mathrm{V}_{\mathrm{DS}}=\mathrm{V}_{\mathrm{Gs}}, \mathrm{ld}=250 \mu \mathrm{~A}$ | 2 | 3 | 4 | V |
| RDS(on) | Static drain-source onresistance | $\mathrm{VGS}=10 \mathrm{~V}, \mathrm{ld}=15 \mathrm{~A}$ |  | 0.038 | 0.045 | $\Omega$ |

## Notes

${ }^{(1)}$ Defined by design, not subject to production test.

Table 5: Dynamic

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{gfs}^{(1)}$ | Forward transconductance | $\mathrm{V}_{\mathrm{DS}}=15 \mathrm{~V}, \mathrm{ld}=15 \mathrm{~A}$ | - | 10 | - | S |
| Ciss | Input capacitance | $\mathrm{V}_{\mathrm{DS}}=25 \mathrm{~V}, \mathrm{f}=1 \mathrm{MHz}, \mathrm{V}_{\mathrm{GS}}=0 \mathrm{~V}$ | - | 1200 | - | pF |
| Coss | Output capacitance |  | - | 180 | - | pF |
| Crss | Reverse transfer capacitance |  | - | 80 | - | pF |
| $\mathrm{Q}_{\mathrm{g}}$ | Total gate charge | $\begin{aligned} & \mathrm{V}_{\mathrm{DD}}=80 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=30 \mathrm{~A} \\ & \mathrm{~V}_{\mathrm{GS}}=10 \mathrm{~V} \\ & \mathrm{R}_{\mathrm{G}}=4.7 \Omega \end{aligned}$ <br> See Figure 15: "Test circuit for gate charge behavior" |  | 40 | 55 | nC |
| $\mathrm{Q}_{\mathrm{gs}}$ | Gate-source charge |  | - | 8 | - | nC |
| $Q_{g d}$ | Gate-drain charge |  | - | 15 | - | nC |

## Notes:

${ }^{(1)}$ Pulsed: pulse duration $=300 \mu \mathrm{~s}$, duty cycle $1.5 \%$.

Table 6: Switching times

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{t}_{\mathrm{d}(\mathrm{on})}$ | Turn-on delay time | $\begin{aligned} & \mathrm{V}_{\mathrm{DD}}=50 \mathrm{~V}, \mathrm{ID}=15 \mathrm{~A}, \mathrm{R}_{\mathrm{G}}=4.7 \Omega, \\ & \mathrm{~V}_{\mathrm{GS}}=10 \mathrm{~V} \end{aligned}$ <br> See Figure 14: "Test circuit for resistive load switching times" and Figure 19: "Switching time waveform" | - | 15 | - | ns |
| tr | Rise time |  | - | 40 | - | ns |
| $\mathrm{td}_{\text {(off) }}$ | Turn-off delay time |  | - | 45 | - | ns |
| tf | Fall time |  | - | 10 | - | ns |

Table 7: Source-drain diode

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
| :---: | :--- | :--- | :---: | :---: | :---: | :---: |
| $\mathrm{I}_{\mathrm{SD}}$ | Source-drain <br> current |  | - |  | 30 | A |
| $\mathrm{ISDM}^{(1)}$ | Source-drain <br> current (pulsed) |  | - |  | 120 | A |
| $\mathrm{~V}_{\mathrm{SD}}{ }^{(2)}$ | Forward on <br> voltage | $\mathrm{I}_{\mathrm{SD}}=20 \mathrm{~A}, \mathrm{~V}$ GS $=0 \mathrm{~V}$ | - |  | 1.3 | V |
| $\mathrm{t}_{\text {rr }}$ | Reverse recovery <br> time | $\mathrm{ISD}=30 \mathrm{~A}, \mathrm{di} / \mathrm{dt}=100 \mathrm{~A} / \mu \mathrm{S}$, <br> $\mathrm{V}_{\mathrm{DD}}=55 \mathrm{~V}$ | - | 110 |  | ns |
| $\mathrm{Q}_{\mathrm{rr}}$ | Reverse recovery <br> charge | $\mathrm{T}_{\mathrm{j}}=150^{\circ} \mathrm{C}$ <br> See Figure 16: "Test circuit for <br> inductive load switching and diode <br> recovery times" | - | 390 |  | nC |
| $\mathrm{I}_{\mathrm{RRM}}$ | Reverse recovery <br> current | 7.5 |  | A |  |  |

## Notes:

${ }^{(1)}$ Pulse width limited by safe operating area.
${ }^{(2)}$ Pulsed: pulse duration $=300 \mu \mathrm{~s}$, duty cycle $1.5 \%$.

### 2.1 Electrical characteristics (curves)




Figure 5: Transfer characteristics


Figure 6: Transconductance


Figure 4: Output characteristics

Figure 7: Static drain-source on-resistance


Figure 8: Gate charge vs. gate-source voltage


Figure 9: Capacitance variations


Figure 10: Normalized gate threshold voltage vs. temperature


Figure 11: Normalized on-resistance vs. temperature


Figure 12: Source-drain diode forward characteristics


Figure 13: Normalized breakdown voltage vs. temperature


## 3 Test circuits



Figure 16: Test circuit for inductive load switching and diode recovery times


Figure 17: Unclamped inductive load test circuit


Figure 18: Unclamped inductive waveform


Figure 19: Switching time waveform


## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK ${ }^{\circledR}$ packages, depending on their level of environmental compliance. ECOPACK ${ }^{\circledR}$ specifications, grade definitions and product status are available at: www.st.com.
ECOPACK ${ }^{\circledR}$ is an ST trademark.

### 4.1 DPAK (TO-252) type A package information

Figure 20: DPAK (TO-252) type A package outline


Table 8: DPAK (TO-252) type A mechanical data

| Dim. | mm |  |  |
| :---: | :---: | :---: | :---: |
|  | Min. | Typ. | Max. |
| A | 2.20 |  | 2.40 |
| A1 | 0.90 |  | 1.10 |
| A2 | 0.03 |  | 0.23 |
| b | 0.64 |  | 0.90 |
| b4 | 5.20 |  | 5.40 |
| c | 0.45 |  | 0.60 |
| c2 | 0.48 |  | 0.60 |
| D | 6.00 |  | 6.20 |
| D1 | 4.95 |  | 5.25 |
| E | 6.40 |  | 6.60 |
| E1 | 4.60 |  | 4.80 |
| e | 2.16 |  | 2.40 |
| e1 | 4.40 |  | 4.60 |
| H | 9.35 |  | 10.10 |
| L | 1.00 |  | 1.50 |
| L1) | 2.60 |  | 3.00 |
| L2 | 0.65 | 0.80 | 0.95 |
| L4 | 0.60 |  | 1.00 |
| R |  |  | 80 |
| V2 | $0 \circ$ |  |  |

### 4.2 DPAK (TO-252) type C package information

Figure 21: DPAK (TO-252) type C package outline


Table 9: DPAK (TO-252) type C mechanical data

| Dim. | mm |  |  |
| :---: | :---: | :---: | :---: |
|  | Min. | Typ. | Max. |
| A | 2.20 | 2.30 | 2.38 |
| A1 | 0.90 | 1.01 | 1.10 |
| A2 | 0.00 |  | 0.10 |
| b | 0.72 |  | 0.85 |
| b4 | 5.13 | 5.33 | 5.46 |
| c | 0.47 |  | 0.60 |
| c2 | 0.47 |  | 0.60 |
| D | 6.00 | 6.10 | 6.20 |
| D1 | 5.25 |  |  |
| E | 6.50 | 6.60 | 6.70 |
| E1 | 4.70 |  |  |
| e | 2.186 | 2.286 | 2.386 |
| H | 9.80 | 10.10 | 10.40 |
| L | 1.40 | 1.50 | 1.70 |
| L1 | 2.90 REF |  |  |
| L2 | 0.90 |  | 1.25 |
| L3 | 0.51 BSC |  |  |
| L4 | 0.60 | 0.80 | 1.00 |
| L6 | 1.80 BSC |  |  |
| $\theta 1$ | $5^{\circ}$ | $7^{\circ}$ | $9{ }^{\circ}$ |
| $\theta 2$ | $5^{\circ}$ | $7^{\circ}$ | $9^{\circ}$ |
| V2 | $0^{\circ}$ |  | $8^{\circ}$ |

Figure 22: DPAK (TO-252) recommended footprint (dimensions are in mm)


### 4.3 DPAK (TO-252) packing information

Figure 23: DPAK (TO-252) tape outline


Figure 24: DPAK (TO-252) reel outline


Table 10: DPAK (TO-252) tape and reel mechanical data

| Tape |  |  | Reel |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: |
| Dim. | $\mathbf{m m}$ |  | Dim. | $\mathbf{m m}$ |  |
|  | Min. | Max. |  | Min. | Max. |
| A0 | 6.8 | 7 | A |  | 330 |
| B0 | 10.4 | 10.6 | B | 1.5 |  |
| B1 |  | 12.1 | C | 12.8 | 13.2 |
| D | 1.5 | 1.6 | D | 20.2 |  |
| D1 | 1.5 |  | G | 16.4 | 18.4 |
| E | 1.65 | 1.85 | N | 50 |  |
| F | 7.4 | 7.6 | T |  | 22.4 |
| K0 | 2.55 | 2.75 |  |  |  |
| P0 | 3.9 | 4.1 |  | Base qty. | 2500 |
| P1 | 7.9 | 8.1 |  | Bulk qty. | 2500 |
| P2 | 1.9 | 2.1 |  |  |  |
| R | 40 |  |  |  |  |
| T | 0.25 | 0.35 |  |  |  |
| W | 15.7 | 16.3 |  |  |  |

## 5 Revision history

Table 11: Document revision history

| Date | Revision | Changes |
| :---: | :---: | :--- |
| 06-Apr-2016 | 1 | First release. |

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